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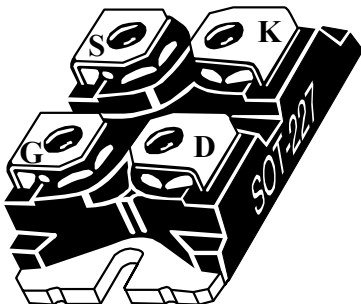
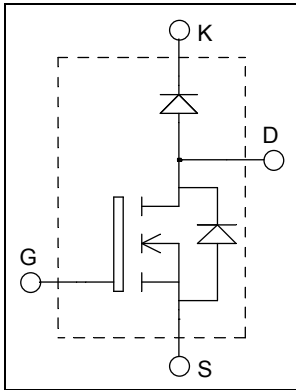
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**ISOTOP<sup>®</sup> Boost chopper  
MOSFET Power Module**

**$V_{DSS} = 500V$**   
 **$R_{DSon} = 65m\Omega \text{ Max @ } T_j = 25^\circ C$**   
 **$I_D = 58A \text{ @ } T_c = 25^\circ C$**



**Application**

- AC and DC motor control
- Switched Mode Power Supplies
- Power Factor Correction
- Brake switch

**Features**

- Power MOS 8<sup>TM</sup> MOSFETs
  - Low  $R_{DSon}$
  - Low input and Miller capacitance
  - Low gate charge
  - Avalanche energy rated
  - Very rugged
- ISOTOP<sup>®</sup> Package (SOT-227)
- Very low stray inductance
- High level of integration

**Benefits**

- Outstanding performance at high frequency operation
- Stable temperature behavior
- Very rugged
- Direct mounting to heatsink (isolated package)
- Low junction to case thermal resistance
- Easy paralleling due to positive TC of VCEsat
- RoHS Compliant

**Absolute maximum ratings**

Symbol	Parameter	Max ratings	Unit
$V_{DSS}$	Drain - Source Breakdown Voltage	500	V
$I_D$	Continuous Drain Current	$T_c = 25^\circ C$	58
		$T_c = 80^\circ C$	43
$I_{DM}$	Pulsed Drain current	270	A
$V_{GS}$	Gate - Source Voltage	$\pm 30$	
$R_{DSon}$	Drain - Source ON Resistance	65	m $\Omega$
$P_D$	Maximum Power Dissipation	$T_c = 25^\circ C$	543
$I_{AR}$	Avalanche current (repetitive and non repetitive)	42	A

 **CAUTION:** These Devices are sensitive to Electrostatic Discharge. Proper Handling Procedures Should Be Followed.

All ratings @  $T_j = 25^\circ\text{C}$  unless otherwise specified

**Electrical Characteristics**

Symbol	Characteristic	Test Conditions	Min	Typ	Max	Unit
$I_{DSS}$	Zero Gate Voltage Drain Current	$V_{DS} = 500\text{V}$ $V_{GS} = 0\text{V}$	$T_j = 25^\circ\text{C}$		250	$\mu\text{A}$
			$T_j = 125^\circ\text{C}$		1000	
$R_{DS(on)}$	Drain – Source on Resistance	$V_{GS} = 10\text{V}, I_D = 42\text{A}$			65	$\text{m}\Omega$
$V_{GS(th)}$	Gate Threshold Voltage	$V_{GS} = V_{DS}, I_D = 2.5\text{mA}$	3	4	5	V
$I_{GSS}$	Gate – Source Leakage Current	$V_{GS} = \pm 30\text{V}$			$\pm 100$	nA

**Dynamic Characteristics**

Symbol	Characteristic	Test Conditions	Min	Typ	Max	Unit
$C_{iss}$	Input Capacitance	$V_{GS} = 0\text{V}$ $V_{DS} = 25\text{V}$ $f = 1\text{MHz}$		10800		pF
$C_{oss}$	Output Capacitance			1164		
$C_{riss}$	Reverse Transfer Capacitance			148		
$Q_g$	Total gate Charge	$V_{GS} = 10\text{V}$ $V_{Bus} = 250\text{V}$ $I_D = 42\text{A}$		340		nC
$Q_{gs}$	Gate – Source Charge			75		
$Q_{gd}$	Gate – Drain Charge			155		
$T_{d(on)}$	Turn-on Delay Time	<b>Resistive switching @ <math>25^\circ\text{C}</math></b> $V_{GS} = 15\text{V}$ $V_{Bus} = 333\text{V}$ $I_D = 42\text{A}$ $R_G = 2.2\Omega$		60		ns
$T_r$	Rise Time			70		
$T_{d(off)}$	Turn-off Delay Time			155		
$T_f$	Fall Time			50		

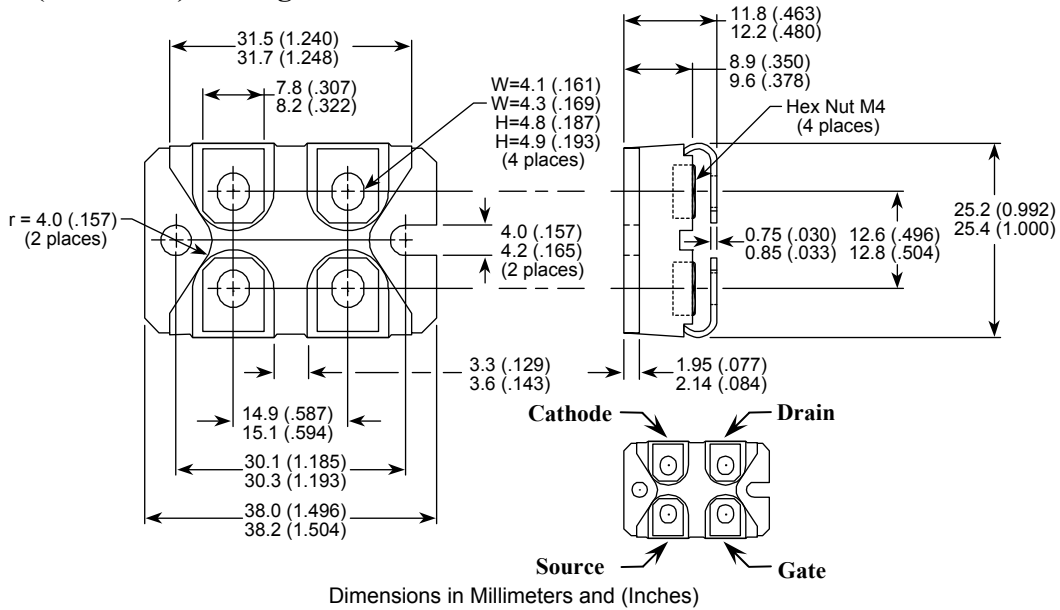
**Chopper diode ratings and characteristics**

Symbol	Characteristic	Test Conditions	Min	Typ	Max	Unit
$V_{RRM}$	Maximum Peak Repetitive Reverse Voltage		600			V
$I_{RM}$	Maximum Reverse Leakage Current	$V_R = 600\text{V}$	$T_j = 25^\circ\text{C}$		25	$\mu\text{A}$
			$T_j = 125^\circ\text{C}$		500	
$I_F$	DC Forward Current	$T_c = 90^\circ\text{C}$		30		A
$V_F$	Diode Forward Voltage	$I_F = 30\text{A}$		1.8	2.2	V
		$I_F = 60\text{A}$		2.2		
		$I_F = 30\text{A}$	$T_j = 125^\circ\text{C}$	1.5		
$t_{rr}$	Reverse Recovery Time	$I_F = 30\text{A}$ $V_R = 400\text{V}$ $di/dt = 200\text{A}/\mu\text{s}$	$T_j = 25^\circ\text{C}$	25		ns
			$T_j = 125^\circ\text{C}$	160		
$Q_{rr}$	Reverse Recovery Charge		$T_j = 25^\circ\text{C}$	35		nC
			$T_j = 125^\circ\text{C}$	480		

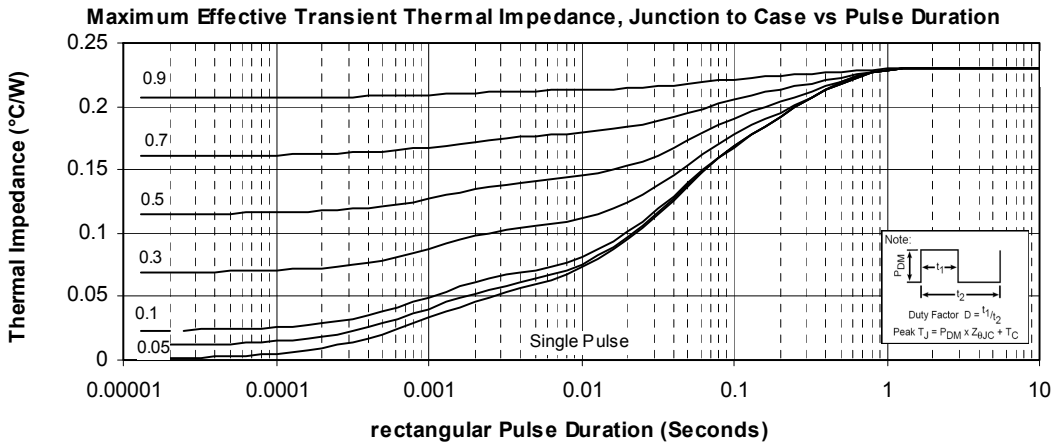
**Thermal and package characteristics**

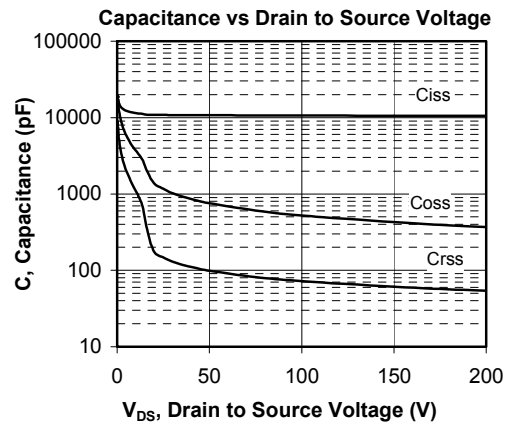
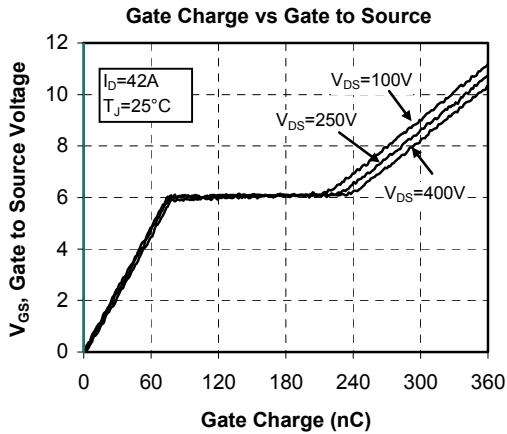
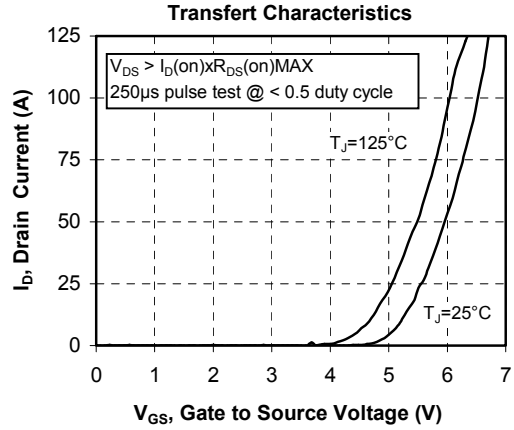
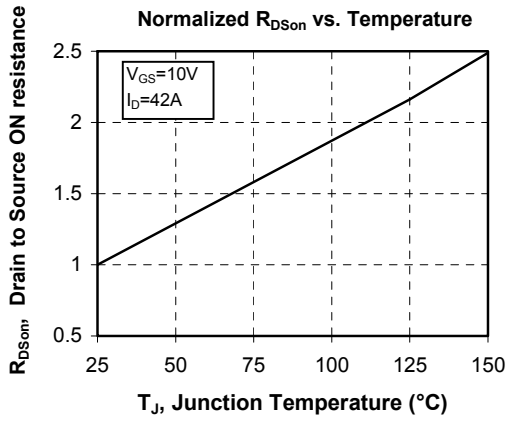
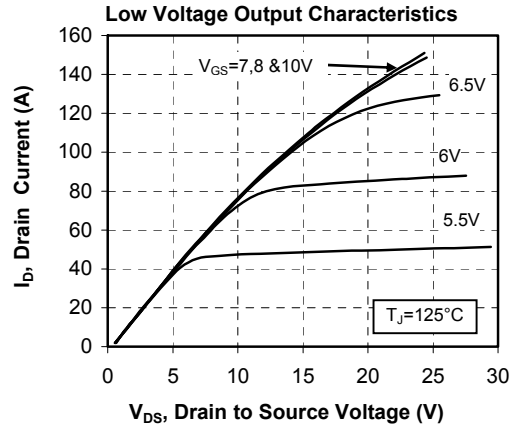
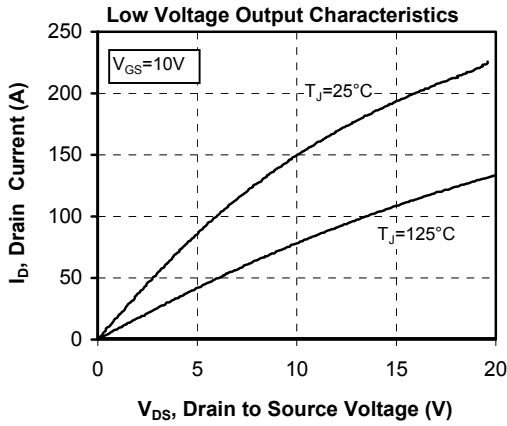
Symbol	Characteristic	Min	Typ	Max	Unit
$R_{thJC}$	Junction to Case Thermal Resistance	Mosfet		0.23	$^\circ\text{C}/\text{W}$
		Diode		1.05	
$R_{thJA}$	Junction to Ambient (IGBT & Diode)			20	$^\circ\text{C}/\text{W}$
$V_{ISOL}$	RMS Isolation Voltage, any terminal to case $t = 1\text{ min}, 50/60\text{Hz}$	2500			V
$T_j, T_{STG}$	Storage Temperature Range	-40		150	$^\circ\text{C}$
$T_L$	Max Lead Temp for Soldering: 0.063" from case for 10 sec			300	
Torque	Mounting torque (Mounting = 8-32 or 4mm Machine and terminals = 4mm Machine)			1.5	N.m
Wt	Package Weight		29.2		g

**SOT-227 (ISOTOP®) Package Outline**

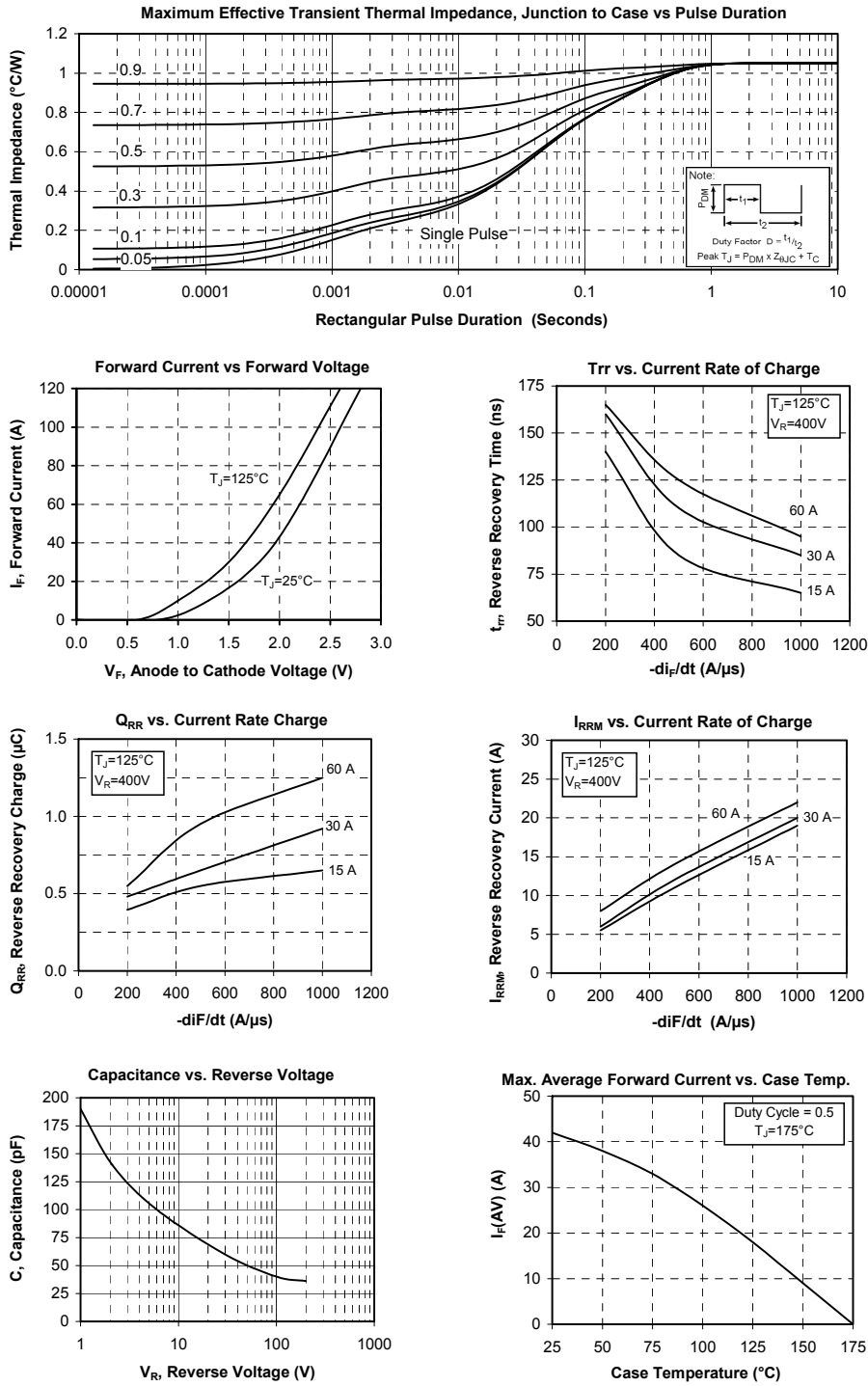


**Typical Mosfet Performance Curve**





## Typical Diode Performance Curve



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